DCN Number	20170217000 PCN Pate: March 22, 2017				March 22, 2017	
PCN Number:				March 22, 2017		
Qualification of Carsem Suzhou (CSZ) as additional Assembly and Test Site for Select Devices						
<b>Customer Contact:</b>	PCN Manager Dept: Quality Services					
Proposed 1 <sup>st</sup> Ship Date	June 22, 20	17 Estima Availa	ted Samp	ole	Date Provided at Sample request	
Change Type:		7100110			- Campio i aquast	
Assembly Site		Design		Wa	fer Bump Site	
Assembly Process		Data Sheet		Wafer Bump Material		
Assembly Materials		Part number c	hange		Wafer Bump Process	
Mechanical Specifica	ntion	Test Site			Wafer Fab Site	
Packing/Shipping/La	beling	Test Process		Wa	fer Fab Materials	
				Wa	fer Fab Process	
		<b>PCN</b> Detai	ls			
<b>Description of Change:</b>						
Texas Instruments Incorp						
Additional Assembly and				Product Affe	cted" Section.	
Current assembly sites a	nd Material diff	erences are as f	follows.			
Assembly Site Assem	bly Site Origin	Assembly Cou	ntry Code	Assembly	/ Site City	
TI Clark	QAB	PHL		Angeles City, Pampanga		
Carsem Suzhou	CSZ	CHN	CHN		igsu	
Material Differences:				_		
	TI Clar	k Carsen	1 Suzhou			
Mount compoun	d 420776	8 43	5143			
Test coverage, insertions, conditions will remain consistent with current testing and verified with test MQ.						
Reason for Change:						
Continuity of Supply						
Anticipated impact on Material Declaration						
No Impact to the Material Declaration	Impact to the terial Declaration   Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the TI ECO website.					
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):						
None					-, -, -, -, -, -, -, -, -, -, -, -, -, -	
None  Changes to product ide				-7 (1-1-1-1		

Assembly Site		
TI Clark Philippines	Assembly Site Origin (22L)	ASO: QAB
Carsem Suzhou	Assembly Site Origin (22L)	ASO: CSZ

Sample product shipping label (not actual product label)



ASSEMBLY SITE CODES: TI-Clark = I, Carsem Suzhou = F

### **Product Affected:**

TLV62095RGTR TLV62095RGTT

# **Qualification Report**

# Qualifying CARZ as 2nd Source for TLV62095RGTR

Approve Date 03-Mar-2017

## **Product Attributes**

Attributes	Qual Device: TLV62095RGTR	QBS Product Reference: TLV62090RGTR	QBS Process Reference: TCA6416PW	QBS Package Reference: SH6966ACC0RGCRG4_AU_WIRE
Assembly Site	CARZ	CLARK-AT	MLA	CLARK-AT
Package Family	QFN 3 X 3 (MM)	QFN	TSSOP	QFN
Flammability Rating	-	UL 94 V-0	UL 94 V 0	UL 94 V-0
Wafer Fab Supplier	FFAB, RFAB	FFAB	FFAB	MIHO8
Wafer Process	LBC7	LBC7	LBC7	LBC7

Attributes	QBS Package Reference: SH6966ACC0RGCRG4_CU_WIRE	QBS Package Reference: TPS62090RGT	QBS Package Reference: TPS62130RGT
Assembly Site	CLARK-AT	CLARK	TI-CLARK
Package Family	QFN	QFN	QFN
Flammability Rating	UL 94 V-0	UL 94 V-0	UL 94 V-0
Wafer Fab Supplier	MIHO8	RFAB	MIHO8
Wafer Process	LBC7	LBC7	LBC7

- QBS: Qual By Similarity
- Qual Device TLV62095RGTR is qualified at LEVEL2-260CG
- Device TLV62095RGTR contains multiple dies

**Qualification Results**Data Displayed as: Number of lots / Total sample size / Total failed

		bata bispia yea asi	variable of lots / 1	otal sample size / 1	otal lanca	
Туре	Test Name / Condition	Duration	Qual Device: TLV62095RGTR	QBS Product Reference: TLV62090RGTR	QBS Process Reference: TCA6416PW	QBS Package Reference: SH6966ACC0RGCR G4_AU_WIRE
AC	Autoclave 121C	96 Hours	-	-	3/231/0	1/77/0
ED	Electrical Characterization	Per Datasheet Parameters	-	Pass	Pass	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	3/231/0	1/77/0
HBM	ESD - HBM	2500 V	-	1/3/0	1/3/0	-
CDM	ESD - CDM	1000 V	-	1/3/0	-	-
HTOL	Life Test, 125C	1000 Hours	-	-	-	1/77/0
HTOL	Life Test, 150C	300 Hours	-	-	3/231/0	-
HTSL	High Temp. Storage Bake, 150C	1000 Hours	-	-	3/231/0	-
HTSL	High Temp. Storage Bake, 170C	420 Hours	-	-	-	1/77/0
LU	Latch-up	(per JESD78)	-	1/6/0	1/9/0	-
PD	Physical Dimensions		-	-	-	1/5/0
SD	Solderability	8 Hours Steam Age	-	-	-	1/22/0
TC	Temperature Cycle, - 65/150C	500 Cycles	-	-	3/231/0	1/77/0
TS	Thermal Shock, - 65/150C	500 Cycles	-	-	-	1/77/0
WBP	Bond Pull	Wires	-	-	-	1/76/0
WBS	Bond Shear	Wires	-	-	-	1/76/0

Туре	Test Name / Condition	Duration	QBS Package Reference: SH6966ACC0RGCRG4_ CU_WIRE	QBS Package Reference: TPS62090RGT	QBS Package Reference: TPS62130RGT
AC	Autoclave 121C	96 Hours	3/231/0	-	1/77/0
ED	Electrical Characterization	Per Datasheet Parameters	-	Pass	Pass
HAST	Biased HAST, 130C/85%RH	96 Hours	3/231/0	-	-
HBM	ESD - HBM	2500 V	-	1/3/0	-
CDM	ESD - CDM	1000 V	-	1/3/0	-
HTOL	Life Test, 125C	1000 Hours	3/231/0	-	-
HTOL	Life Test, 150C	300 Hours	-	1/77/0	1/77/0
HTSL	High Temp. Storage Bake, 150C	1000 Hours	-	-	-
HTSL	High Temp. Storage Bake, 170C	420 Hours	3/231/0	-	-
LU	Latch-up	(per JESD78)	-	1/6/0	1/6/0
PD	Physical Dimensions		3/15/0	-	-
SD	Solderability	8 Hours Steam Age	3/66/0	-	-
TC	Temperature Cycle, - 65/150C	500 Cycles	3/231/0	1/77/0	1/77/0
TS	Thermal Shock, -65/150C	500 Cycles	3/231/0	-	-
WBP	Bond Pull	Wires	3/228/0	-	-
WBS	Bond Shear	Wires	3/228/0	-	-

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com